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Author: Jinyeol Yang Soonkyu Hwang Yun-Kyu An Kyuhang Lee Hoon Sohn



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Multi-spot Laser Lock-in Thermography for Real-time Imaging of Cracks in Semiconductor Chips during a Manufacturing Process

Jinyeol Yang^a, Soonkyu Hwang^a, Yun-Kyu An^{b,*}, Kyuhang Lee^c and Hoon Sohn^a

^aDepartment of Civil and Environmental Engineering, KAIST, Daejeon, 305-701, South Korea

^bDepartment of Architectural Engineering, Sejong University, Seoul, 143-747, South Korea

^cCVI optics co., Ltd, 398 Seokcheon-ro, Ohjung-gu, Bucheon, 421-809, South Korea

*Corresponding author, Professor, e-mail: yunkyu@sejong.ac.kr, Tel: +82-2-6935-2426

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